

IN THE CLAIMS:

1. (Canceled)
2. (Currently Amended) A semiconductor package, comprising:
 - a semiconductor substrate;
 - a plurality of chip pads separately formed on an upper surface of the semiconductor substrate;
 - a first metal pattern formed on an upper surface of ~~the plurality of~~ respective chip pads;
 - a second metal pattern formed on an upper surface of the first metal pattern and having a plurality of bulkheads separately formed on the first metal pattern, wherein a width of the bulkhead is uniform regardless of a height of the bulkhead including an surface, a first side portion, a second side portion, and a third side portion intermediate the first portion and the second side portion, the first side portion and the third side portion defining a space therebetween, and the second side portion and the third portion defining a space therebetween, the second metal pattern having an irregular shape and formed on an upper surface of the first metal pattern; and
 - an external terminal electrically connected to the an upper surface of the second metal pattern and ~~the a side portion of the bulkhead second metal pattern~~ and extending into a space between the plurality of bulkheads into the space defined by the first and third side portions and extending into the space defined by the second and third side portions.

3. (Original) The semiconductor package according to claim 2, wherein the first metal pattern includes titanium.
4. (Original) The semiconductor package according to claim 2, wherein the second metal pattern includes nickel.
5. (Original) The semiconductor package according to claim 2, further comprising:
a first insulation layer formed on a region of the upper surface of the semiconductor substrate not occupied by the plurality of chip pads; and
a second insulation layer formed on upper surfaces of the first insulation layer and the first metal pattern.
6. (Original) The semiconductor package according to claim 5, wherein the first insulation layer includes polyimide or benzocyclobutene.
7. (Original) The semiconductor package according to claim 5, wherein the second insulation layer includes a photoresist layer or benzocyclobutene.
8. (Original) The semiconductor package according to claim 5, further comprising a solder mask formed on an upper surface of the second insulation layer.
9. (Original) The semiconductor package according to claim 5, wherein the external terminal includes a solder ball.

10. (Original) The semiconductor package according to claim 9, wherein the semiconductor substrate includes a wafer.

11-20. (Withdrawn)